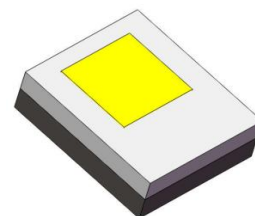


LUWS1FH.01



采用陶瓷封装，便于集成，良好的散热性能；采用倒装芯片，亮度高；白色硅胶填充，抗紫外和高温性能好；

Ceramic package, easy to be integrated, good heat dissipation; Flip-chip technology, high optical output efficiency; White silicone sealed, high transmittance, excellent UV protection and thermal stability;

特点 | Features:

- ▲ 封装：陶瓷封装
Package: Ceramic package
- ▲ 视角：120°
Viewing angle: 120°
- ▲ 颜色：Cx = 0.3217, Cy = 0.3318 根据 CIE 1931 (white)
Color: Cx = 0.3217, Cy = 0.3318 acc. to CIE 1931 (white)
- ▲ ESD：8 千伏，HBM Class 3B
ESD: 8 kV, HBM Class 3B
- ▲ 认证：AEC-Q102
Qualifications: AEC-Q102
- ▲ MSL：等级 2
MSL: Level 2

应用 | Applications:

- ▲ 汽车信号灯
Automotive lights
- ▲ 电器指示灯
Signaling lamp of apparatus
- ▲ 灯具
Lanterns
- ▲ 仪器、仪表盘背光显示
Dashboard backlight

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器件最大允许值 | Maximum Ratings

参数 Parameter	符号 Symbol	值 Values	单位 Unit
工作温度 Operating temperature	T_{op}	-40-125	°C
存储温度 Storage temperature	T_{stg}	-40-125	°C
结温 P/N junction temperature	T_j	150	°C
正向电流 Forward current	I_f	1500	mA
脉冲峰值电流 Surge current ($t \leq 10\mu S$; $D=0.005$; $T_s=25^\circ C$)	I_{fm}	1800	mA
反向击穿电压 Reverse voltage	V_R	not designed for reverse operation	V
抗静电电压 ESD withstand voltage (acc. To ANSI/ESDA/JEDEC JS-001-HBM, Class 3B)	V_{ESD}	8	kV

关键指标参数 | Characteristics (Ts=25°C, If=350mA)

参数 Parameter	符号 Symbol	值 Values	单位 Unit
色温 Color temperature	CCT	typ. 6000	K
色坐标 Chromaticity Coordinate	Cx	typ. 0.3217	
	Cy	typ. 0.3318	
发光角度 Viewing angle at 50% Iv	2θ	typ. 120	deg. [°]
正向电压 Forward voltage		min. 2.6	
	Vf	typ. 3.1	V
		max. 3.4	
光通量 Luminous flux	Φ	typ. 110	lm
反向漏电流 Reverse current	I _R	not designed for reverse operation	μA
热阻 (P/N 结到焊接点) Thermal resistance (P/N junction to soldering point)	R _{th,Js ele}	max. 9	K/W

亮度分档 | Brightness Groups (Ts=25°C, If=350mA)

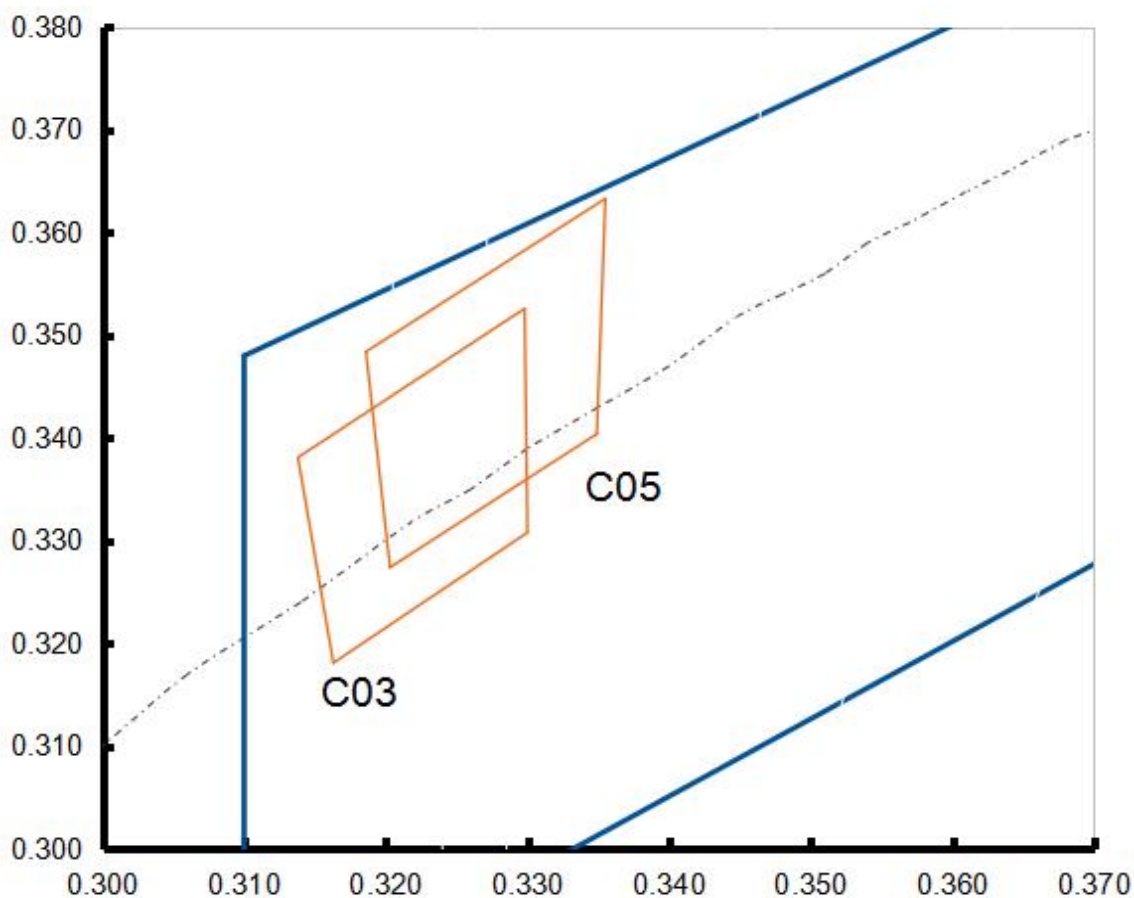
组 Group	符号 Symbol	最小值 Min.	最大值 Max.	单位 Unit
B01	Φ_V	100	110	lm
B02	Φ_V	110	120	lm
B03	Φ_V	120	130	lm
B04	Φ_V	130	140	lm
B05	Φ_V	140	160	lm
B06	Φ_V	160	180	lm
B07	Φ_V	180	200	lm

*Ts: soldering point temperature

电压分档 | Forward Voltage Groups (Ts=25°C, If=350mA)

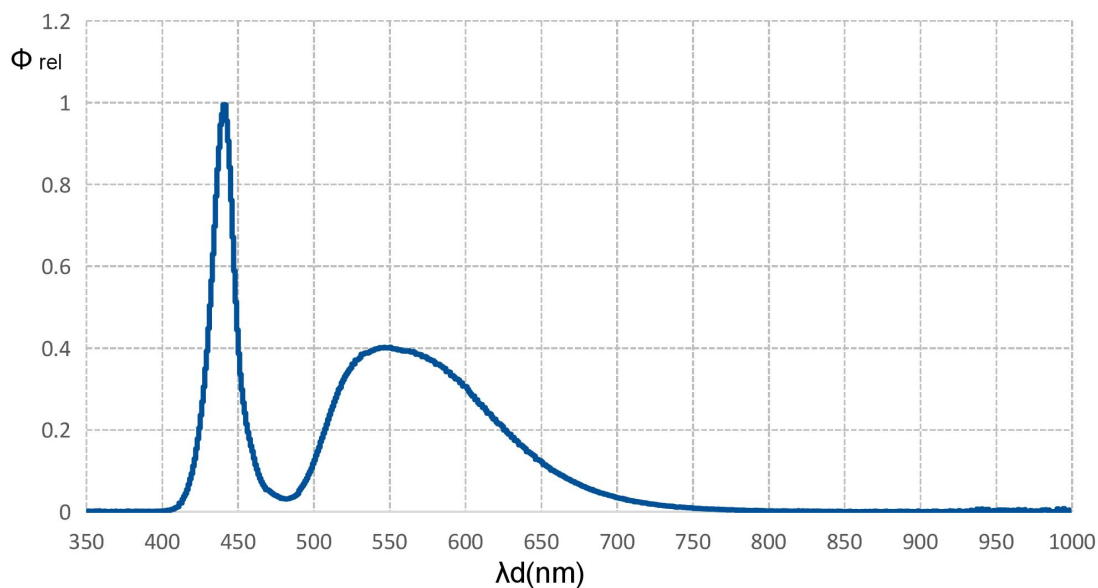
组 Group	符号 Symbol	最小值 Min.	最大值 Max.	单位 Unit
V01	Vf	2.6	2.8	V
V02	Vf	2.8	3.0	V
V03	Vf	3.0	3.2	V
V04	Vf	3.2	3.4	V

色度分档 | Chroma Groups (Ts=25°C, If=350mA)

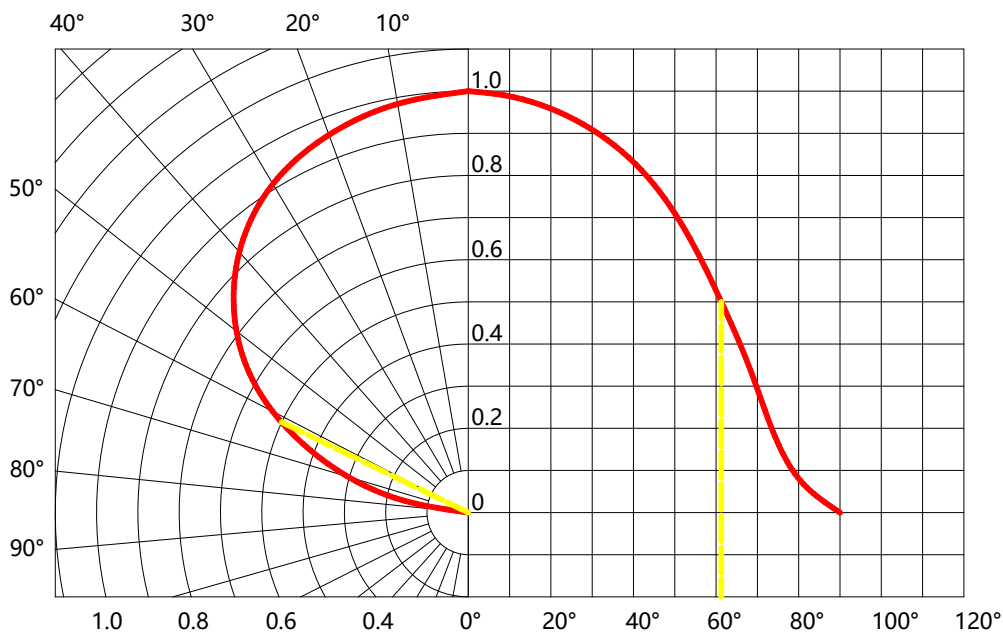


组 Group	符号 Symbol	Cx Cx	Cy Cy	单位 Unit
C03	CCT	0.3138	0.3381	
	CCT	0.3163	0.3181	
	CCT	0.3300	0.3308	
	CCT	0.3298	0.3526	
C05	CCT	0.3186	0.3484	
	CCT	0.3203	0.3274	
	CCT	0.3349	0.3404	
	CCT	0.3355	0.3633	

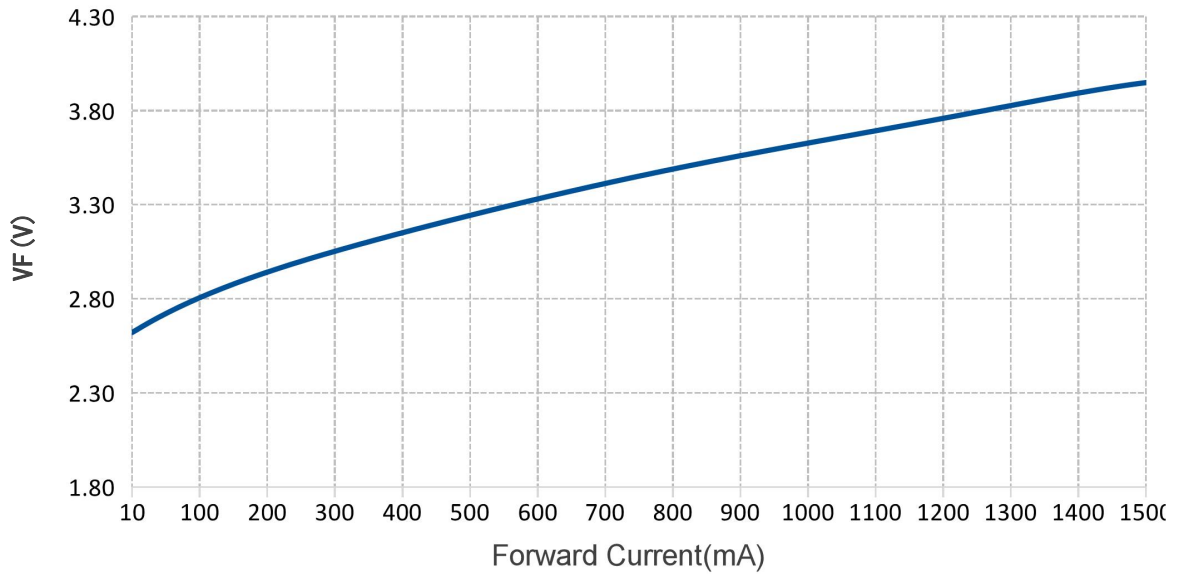
相对光谱分布曲线 | Relative Spectral Emission Curve (Ts=25°C, If=350mA)



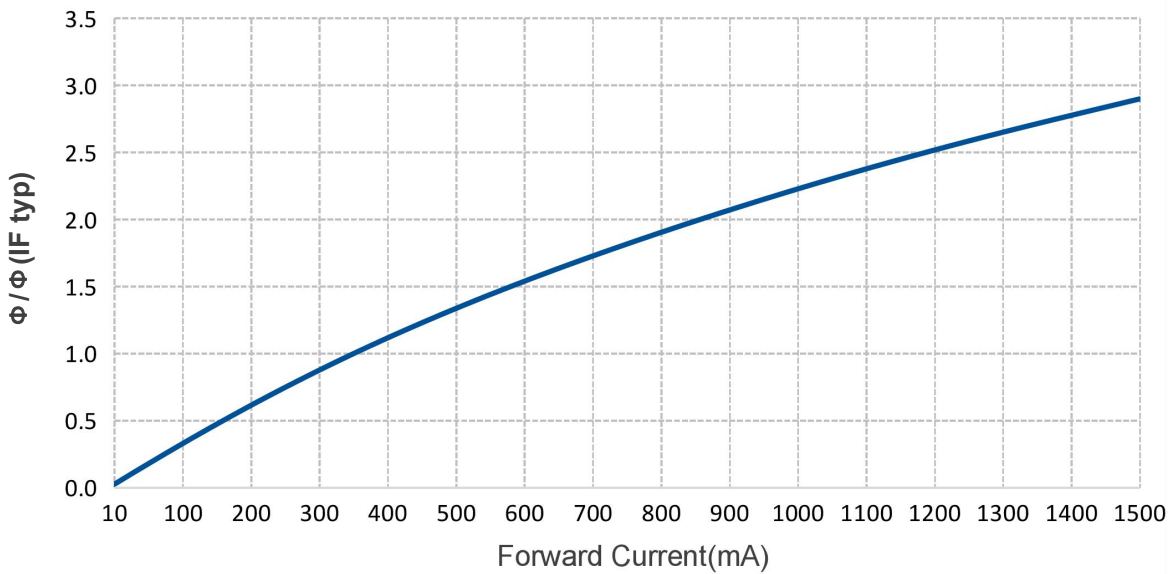
辐射特性 | Radiation Characteristics (Ts=25°C, If=350mA)



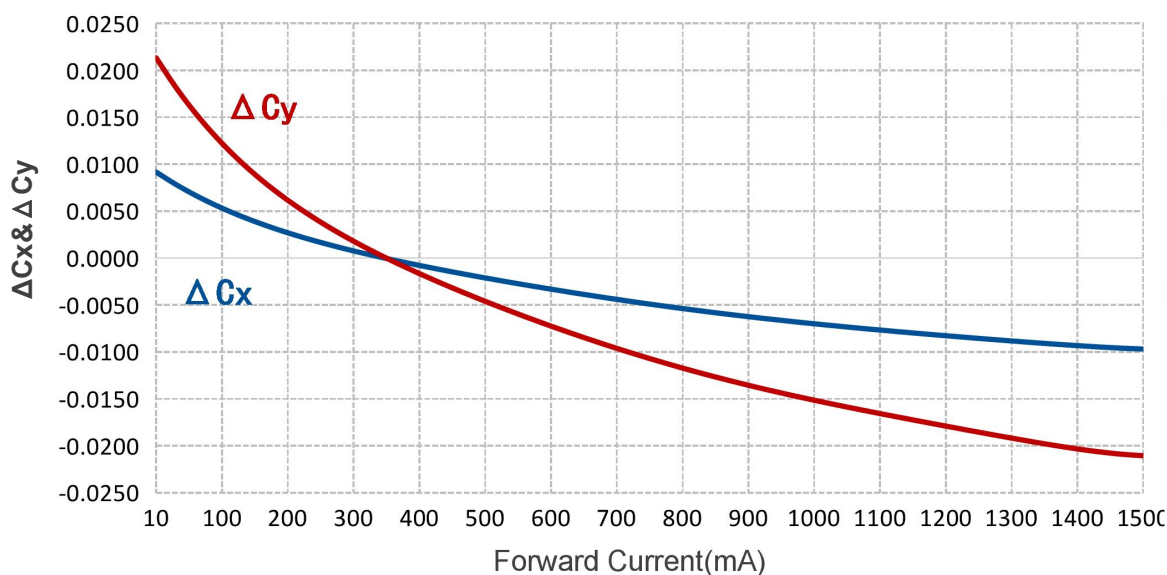
正向电流-正向电压 | Forward current-Forward Voltage (Ts=25°C)



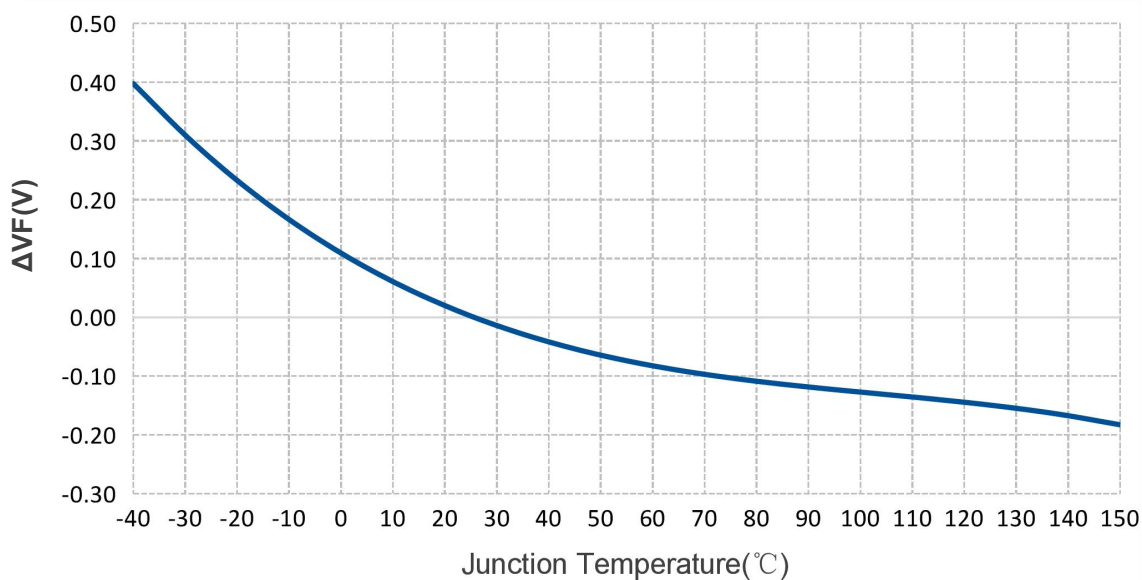
正向电流-相对光通量 | Forward current-Relative Luminous Flux (Ts=25°C)



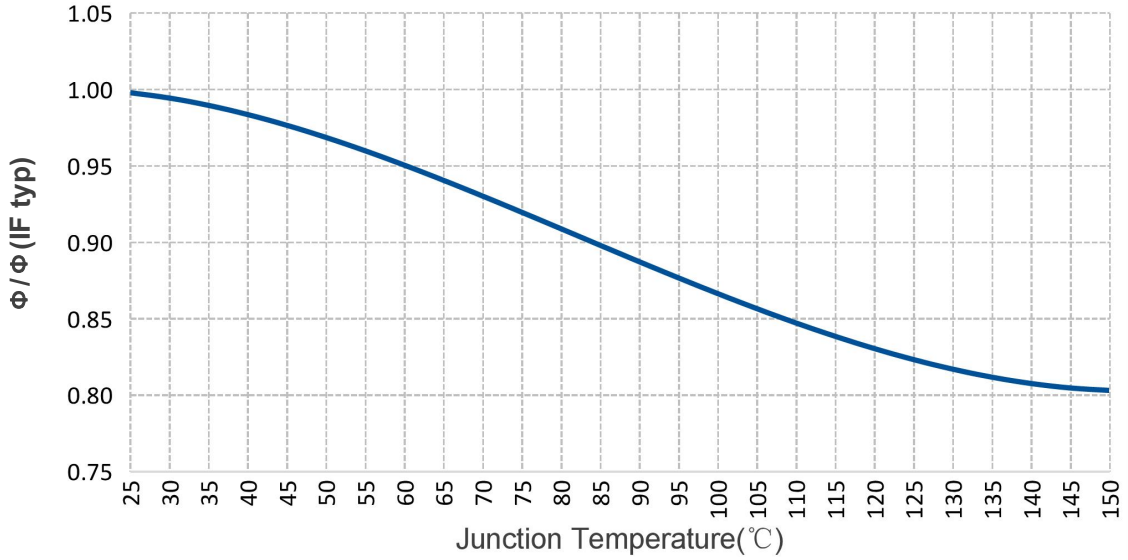
正向电流-色度偏移 | Forward current-Color Shift Characteristics (Ts=25°C)



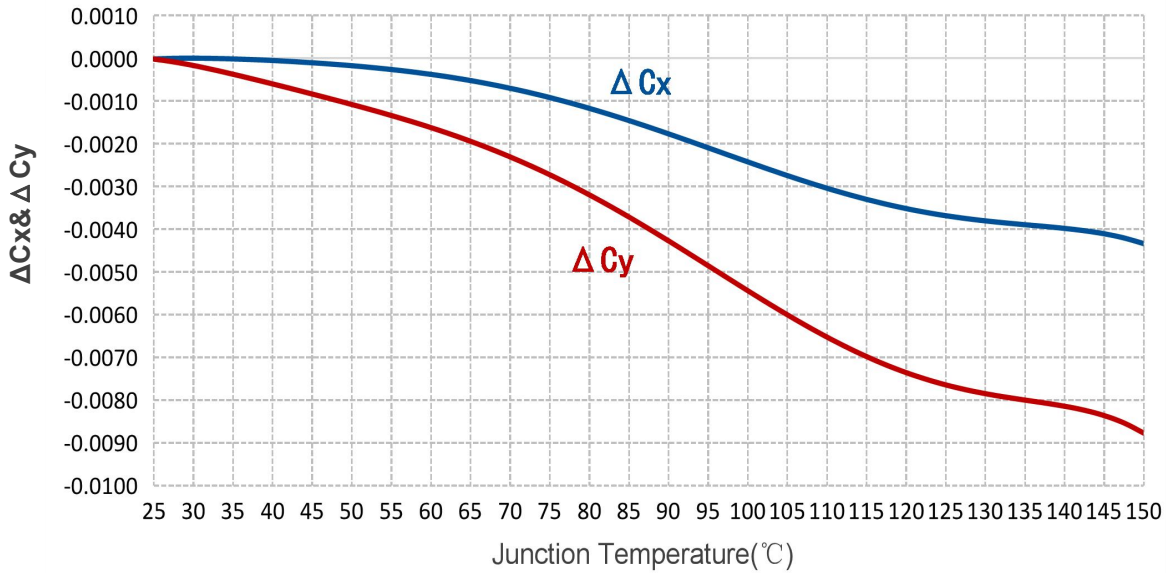
结温-正向电压 | Junction Temperature-Forward Voltage (If=350mA)



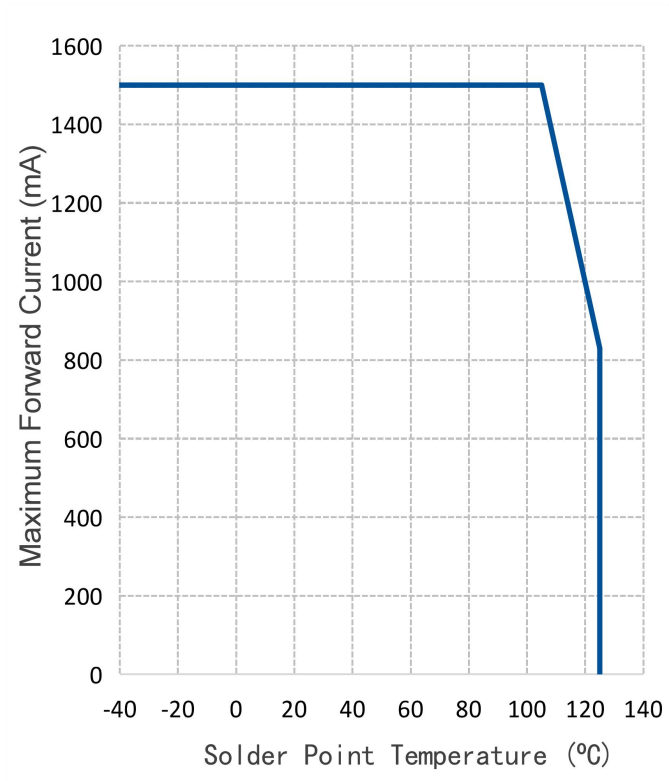
结温-相对光通量 | Junction Temperature-Relative Luminous Flux (If=350mA)



结温-色度偏移 | Junction Temperature-Color Shift Characteristics (If=350mA)

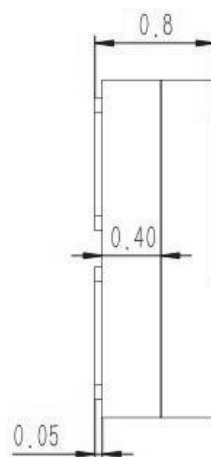
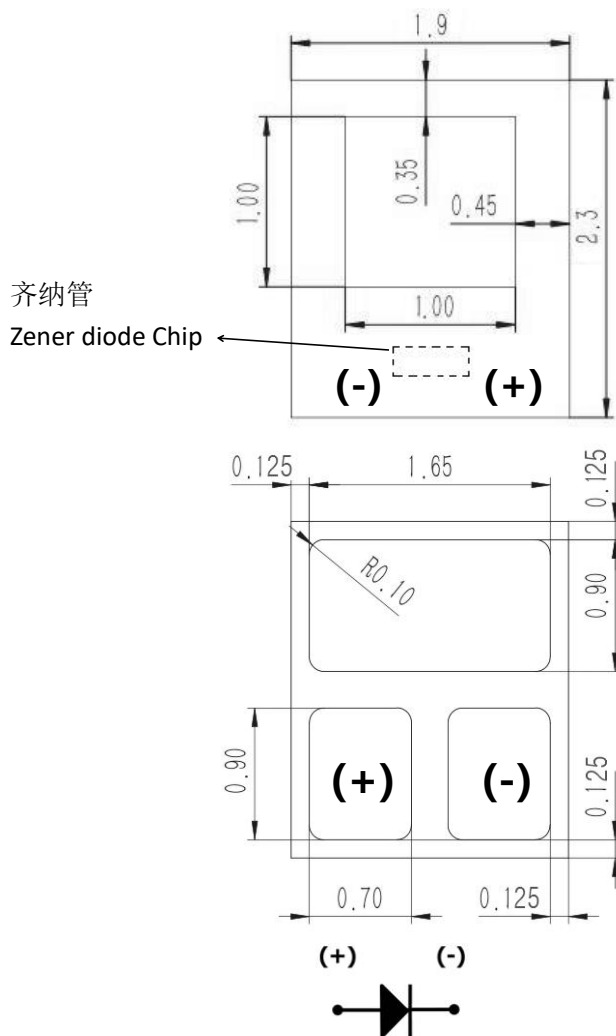


最大容许正向电流 | Max. Permissible Forward Current



外形尺寸 | Mechanical Dimensions

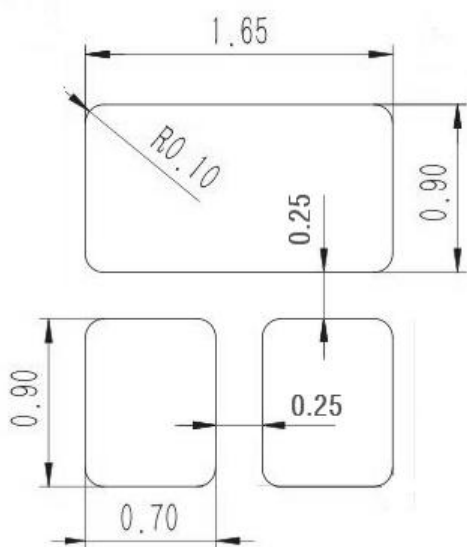
单位 | Unit: mm



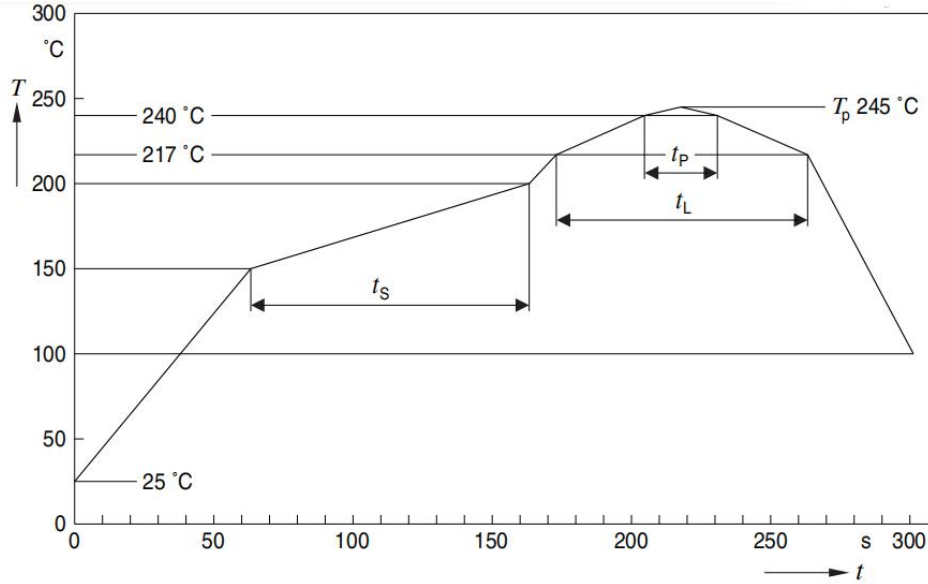
尺寸 Size	公差 Tolerance
.	±0.1mm
*.**	±0.05mm
*.***	±0.05mm

推荐焊盘 | Recommended Solder Pad

单位 | Unit: mm



回流焊曲线 | Reflow Soldering Profile

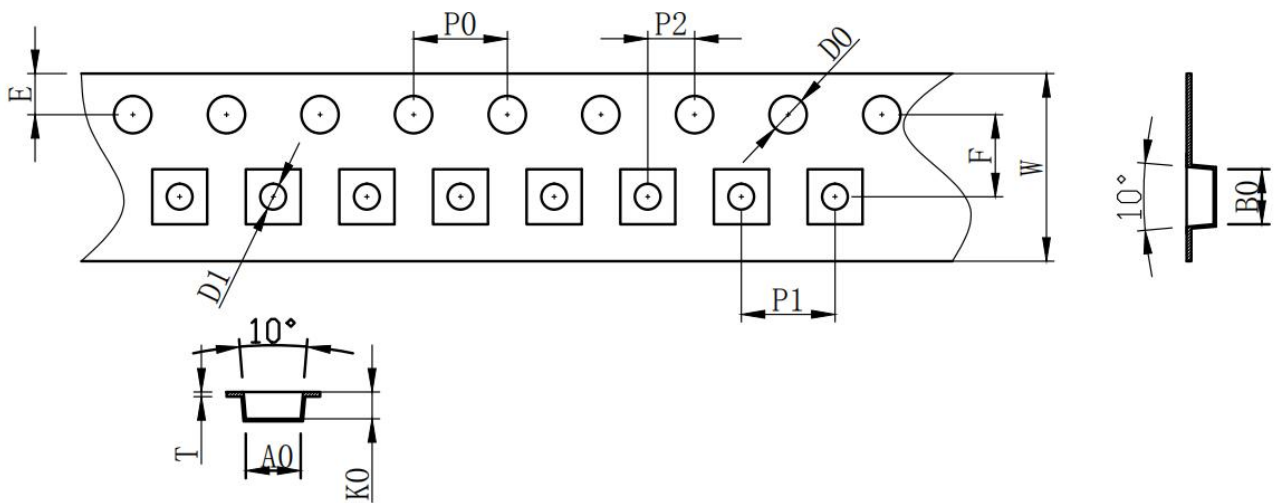
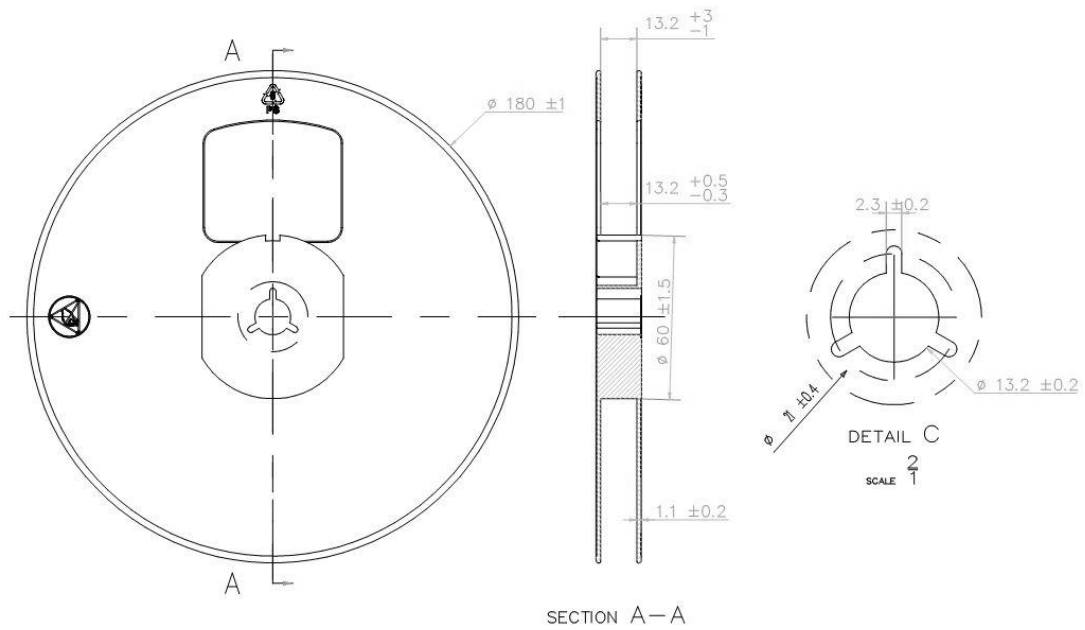


回流焊步骤 Profile Feature	符号 Symbol	无铅回流焊 (SnAgCu) Pb-Free (SnAgCu) Assembly			单位 Unit
		最小值 Min.	设定值 Reco.	最大值 Max.	
预热升温速率 25 °C to 150 °C Ramp-up rate to preheat			2	3	K/s
升温时间 (T_{smin} - T_{smax})	t_s	60	100	120	s
从 T_{smax} 升温到最高温度的速率 Ramp-up rate to peak			2	3	K/s
达到液相的温度 Liquidus temperature			217		°C
在液相温度以上的时间 Time above liquidus temperature	t_L		80	100	s
最高温度 Peak temperature	T_p		245	260	°C
在高于最高温度 5°C 范围内停留的时间 Time within 5 °C of the specified peak temperature $T_p - 5$ K	t_p	10	20	30	s
降到 100°C 的速率 Ramp-down rate* T_p to 100 °C			3	6	K/s
从最高温降到 25°C 的时间 Time 25 °C to T_p				480	s

*LED complies to MSL Level 2 (JEDEC J-STD-020E)

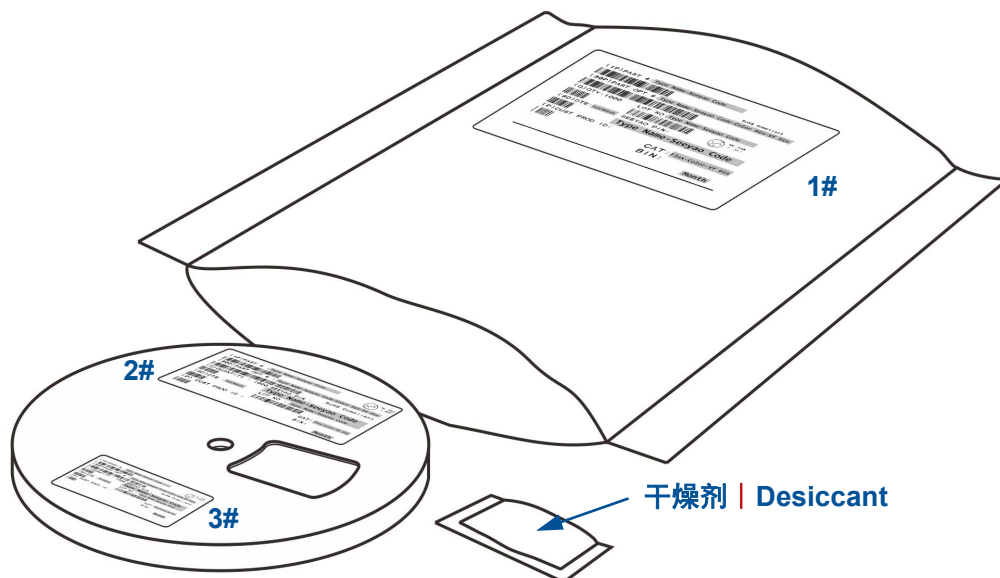
编带 | Taping

单位 | Unit: mm



ITEM	W	A0	B0	K0	E	F	D0	D1	P0	P1	P2	T
DIM	8.00	2.20	2.60	1.00	1.75	3.50	1.50	1.10	4.00	4.00	2.00	0.22
TOLE	+0.10 -0.10	+0.10 -0.10	+0.10 -0.10	+0.10 -0.10	+0.10 -0.10	+0.10 -0.10	+0.10 -0	+0.10 -0.10	+0.10 -0.10	+0.10 -0.10	+0.10 -0.10	+0.03 -0.03

包装信息-产品标签 | Packaging Information- Product Label



标签 1# | Label 1#

(1P) PART # : Type Name-Seeeyao Code
 RoHS Compliant
 (30P) PART OPT # : Type Name-Seeeyao Code-Color Bin-Vf Bin
 (Q) QTY : 1000 LOT NO : Type Name-Seeeyao Code
 (9D) DTE : YearWeek SEEYAO P/N :
 Type Name-Seeeyao Code
 (P) CUST PROD ID : CAT : Flux-Color-Vf Bin
 BIN :
 Month

标签 2# | Label 2#

(1P) PART # : Type Name-Seeeyao Code
 RoHS Compliant
 (30P) PART OPT # : Type Name-Seeeyao Code-Color Bin-Vf Bin
 (Q) QUANTITY : 1000 SEEYAO P/N :
 Type Name-Seeeyao Code
 (9D) DTE : YearWeek LOT NO : Type Name-Seeeyao Code
 (P) CUST PROD ID : CAT : Flux-Color-Vf Bin
 BIN :
 Month

标签 3# | Label 3#

DT: 0123456789
 Num: 1000
 Bin: Bin012#
 ABCDEF-GH0123456789
 SALME0123456789
 Bin0123456789012345